

XP-002183614

AN - 1983-50724K [21]
A - [001] 013 038 04- 075 080 140 154 180 213 214 215 216 231 262 273 293
328 344 346 355 359 398 431 442 465 473 477 50& 532 533 534 536 537
546 57- 575 596 623 627 628 681 689
AP - JP19810164653 19811015
CPY - KOBE
DC - A21 A85 L03 P73
FS - CPI;GMPI
IC - B32B5/22 ; C08J5/24
KS - 0004 0034 0037 0206 0231 1277 1357 1359 1389 1517 2020 2043 2064 2148
2152 2172 2198 2317 2427 2436 2492 2493 2506 2509 2572 2575 2654 2725
2740 3248
MC - A05-C01 A11-B09A A12-B03 A12-E07A L03-H04E1
PA - (KOBE) SHIN KOBE ELECTRIC MACHINERY
PN - JP58065649 A 19830419 DW198321 004pp
- JP61043191B B 19860926 DW198643 000pp
PR - JP19810164653 19811015
XA - C1983-049316
XIC - B32B-005/22 ; C08J-005/24
XP - N1983-090898
AB - J58065649 Mfr. comprises (a) impregnating paper with varnish
consisting of (i) water-sol. phenol resin and (ii) chelating agents
producing water-insol. chelates by reacting with silver ions; (b)
heating the paper and drying it; (c) impregnating with another
varnish; and (d) heating the paper and drying it.
- Migration of silver atoms from one printed circuit to another is
prevented. The chelating agent is e.g. EDTA or diphenylthiocarbazone.
The amts. of chelating agents used are pref. 0.1-5 pts. wt. based on
100 pts. wt. phenol resin. The varnish used in (c) is pref. lipophilic
phenol resin.
AW - PRINT CIRCUIT BOARD
AKW - PRINT CIRCUIT BOARD
IW - SILVER MIGRATION FREE PCB LAMINATE PREPARATION IMPREGNATE PAPER WATER
SOLUBLE POLYPHENOL RESIN CHELATE AGENT REACT SILVER ION HEAT DRY
IKW - SILVER MIGRATION FREE PCB LAMINATE PREPARATION IMPREGNATE PAPER WATER
SOLUBLE POLYPHENOL RESIN CHELATE AGENT REACT SILVER ION HEAT DRY
NC - 001
OPD - 1981-10-15
ORD - 1983-04-19
PAW - (KOBE) SHIN KOBE ELECTRIC MACHINERY
TI - Silver migration-free PCB laminate prep. - by impregnating paper with
water-soluble phenol] resin and chelating agent reacting with silver
ion, heating, drying etc.